BYV430J-600P

Dual ultrafast power diode

3 May 2017 **Product data sheet**

1. General description

Dual ultrafast power diodes in a TO3PF plastic package.

2. Features and benefits

- Very low on-state loss
- Reduces switching losses in associated MOSFET or IGBT
- Low leakage current
- Isolated plastic package

3. Applications

- Active PFC in air conditioner
- S.M.P.S Power Factor Correction (PFC)
- Half-bridge / full-bridge switched-mode power supplies

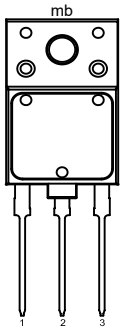
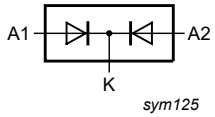
4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_R	reverse voltage	DC		-	-	600	V
$I_{F(AV)}$	average forward current	δ = 0.5 ; $T_h \leq$ 64 °C; square-wave pulse; per diode; Fig. 1; Fig. 2; Fig. 3		-	-	30	A
I_{FRM}	repetitive peak forward current	δ = 0.5 ; t_p = 25 µs; square-wave pulse		-	-	60	A
I_{FSM}	non-repetitive peak forward current	t_p = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse; per diode; Fig. 4		-	-	180	A
		t_p = 8.3 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse; per diode		-	-	200	A
Static characteristics							
V_F	forward voltage	I_F = 30 A; T_j = 25 °C; Fig. 6		-	1.5	2	V
		I_F = 30 A; T_j = 150 °C; Fig. 6		-	1.25	-	V
Dynamic characteristics							
t_{rr}	reverse recovery time	I_F = 30 A; V_R = 30 V; dI_F/dt = 200 A/µs; T_j = 25 °C; Fig. 7		-	53	90	ns
		I_F = 30 A; V_R = 200 V; dI_F/dt = 200 A/µs; T_j = 25 °C; Fig. 7		-	64	-	ns
		I_F = 30 A; V_R = 200 V; dI_F/dt = 200 A/µs; T_j = 125 °C; Fig. 7		-	113	-	ns

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	A1	anode 1	 TO3PF	
2	K	cathode		
3	A2	anode 2		
mb	mb	mounting base		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BYV430J-600P	TO3PF	Plastic single-ended package; isolated heatsink mounted; 1 mounting hole; 3-lead TO-3P 'full pack'	TO3PF

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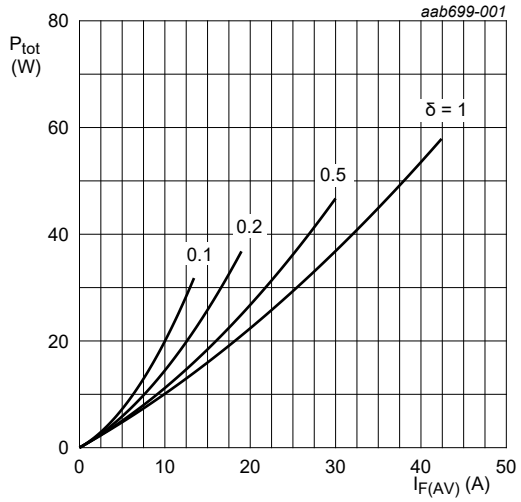
7. Limiting values

Table 4. Limiting values

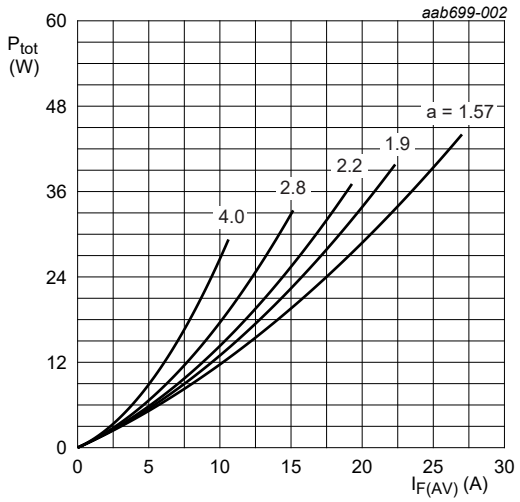
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{RRM}	repetitive peak reverse voltage			-	600	V
V_{RWM}	crest working reverse voltage			-	600	V
V_R	reverse voltage	DC		-	600	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$; $T_h \leq 64$ °C; square-wave pulse; per diode; Fig. 1; Fig. 2; Fig. 3		-	30	A
I_{FRM}	repetitive peak forward current	$\delta = 0.5$; $t_p = 25$ µs; square-wave pulse		-	60	A
I_{FSM}	non-repetitive peak forward current	$t_p = 10$ ms; $T_{j(init)} = 25$ °C; sine-wave pulse; per diode; Fig. 4		-	180	A
		$t_p = 8.3$ ms; $T_{j(init)} = 25$ °C; sine-wave pulse; per diode		-	200	A
T_{stg}	storage temperature			-55	175	°C
T_j	junction temperature			-	175	°C



$I_{F(AV)} = I_{F(RMS)} \times \sqrt{\delta}$
$V_o = 0.899$ V; $R_s = 0.0110$ Ω

Fig. 1. Forward power dissipation as a function of average forward current; square waveform; typical values; per diode



a = form factor = $I_{F(RMS)} / I_{F(AV)}$
$V_o = 0.899$ V; $R_s = 0.0110$ Ω

Fig. 2. Forward power dissipation as a function of average forward current; sinusoidal waveform; typical values; per diode

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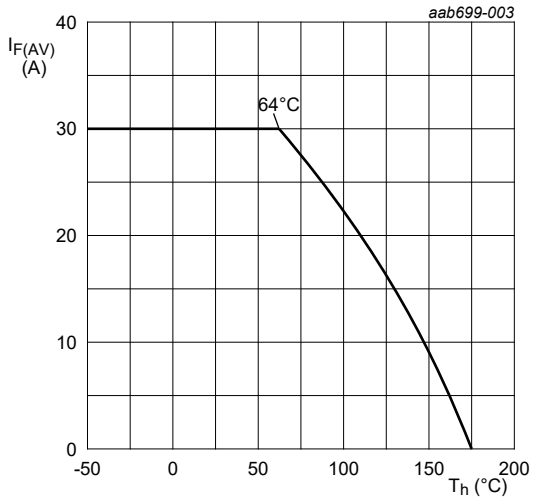

Fig. 3. Average forward current as a function of heatsink temperature; typical values; per diode

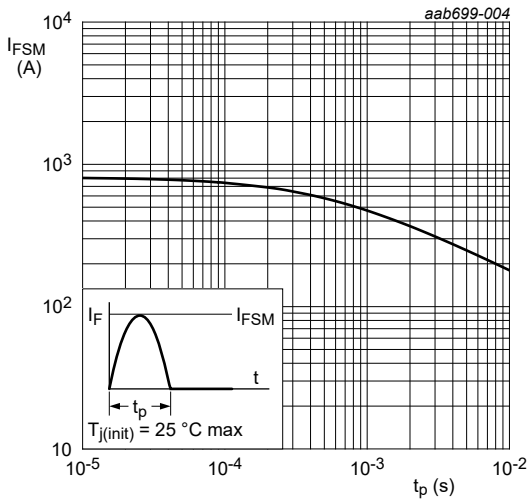

Fig. 4. Non-repetitive peak forward current as a function of pulse width; sinusoidal waveform; maximum values; per diode

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8. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-h)}$	thermal resistance from junction to heatsink	with heatsink compound; per diode; Fig. 5		-	2.4	2.7	K/W
		with heatsink compound; both diodes conducting		-	1.75	2.2	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air		-	35	-	K/W

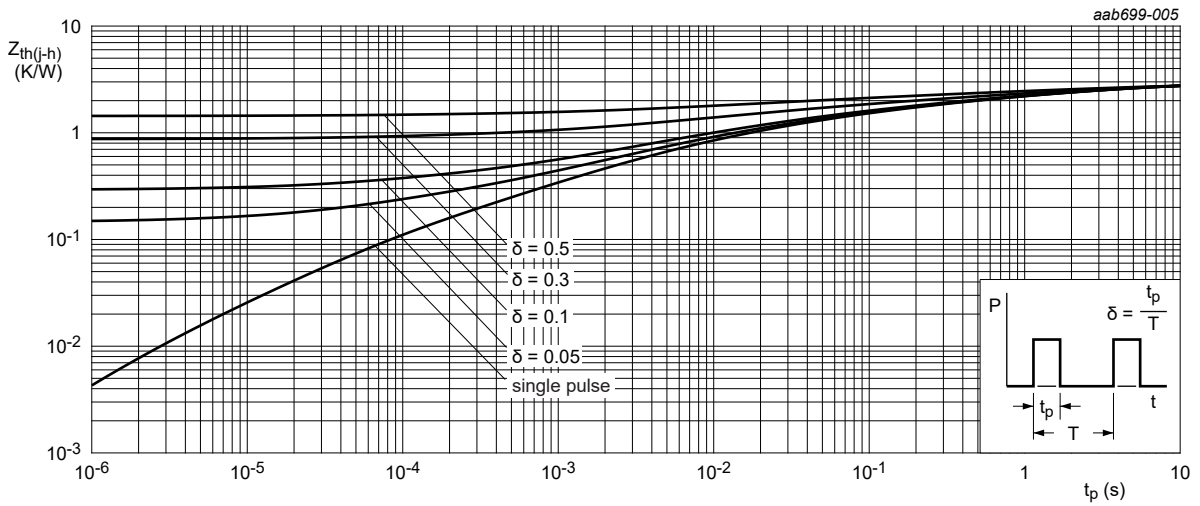

Fig. 5. Transient thermal impedance from junction to heatsink as a function of pulse duration; maximum values; per diode

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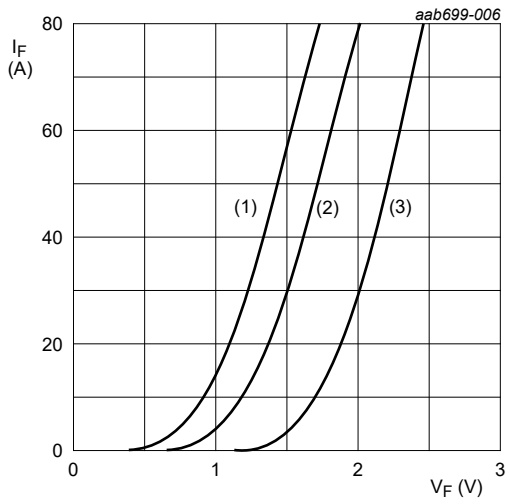
9. Characteristics

Table 6. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
V_F	forward voltage	I_F = 30 A; T_j = 25 °C; Fig. 6		-	1.5	2	V
		I_F = 30 A; T_j = 150 °C; Fig. 6		-	1.25	-	V
I_R	reverse current	V_R = 600 V; T_j = 25 °C		-	-	10	µA
		V_R = 600 V; T_j = 150 °C		-	-	500	µA
Dynamic characteristics							
t_{rr}	reverse recovery time	I_F = 30 A; V_R = 30 V; dI_F/dt = 200 A/µs; T_j = 25 °C; Fig. 7		-	53	90	ns
		I_F = 30 A; V_R = 200 V; dI_F/dt = 200 A/µs; T_j = 25 °C; Fig. 7		-	64	-	ns
		I_F = 30 A; V_R = 200 V; dI_F/dt = 200 A/µs; T_j = 125 °C; Fig. 7		-	113	-	ns
I_{RM}	peak reverse recovery current	I_F = 30 A; V_R = 200 V; dI_F/dt = 200 A/µs; T_j = 25 °C; Fig. 7		-	7.3	-	A
		I_F = 30 A; V_R = 200 V; dI_F/dt = 200 A/µs; T_j = 125 °C; Fig. 7		-	13.5	-	A
Q_r	recovered charge	I_F = 30 A; V_R = 200 V; dI_F/dt = 200 A/µs; T_j = 25 °C; Fig. 7		-	245	-	nC
		I_F = 30 A; V_R = 200 V; dI_F/dt = 200 A/µs; T_j = 125 °C; Fig. 7		-	760	-	nC



(1) T_j = 150 °C; typical values
(2) T_j = 150 °C; maximum values
(3) T_j = 25 °C; maximum values

Fig. 6. Forward current as a function of forward voltage, per diode

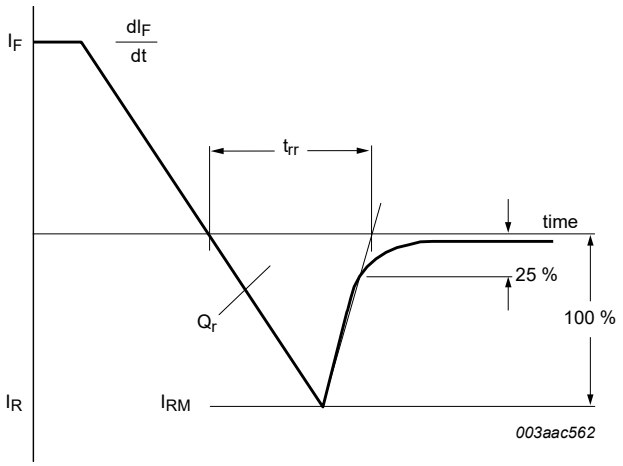


Fig. 7.

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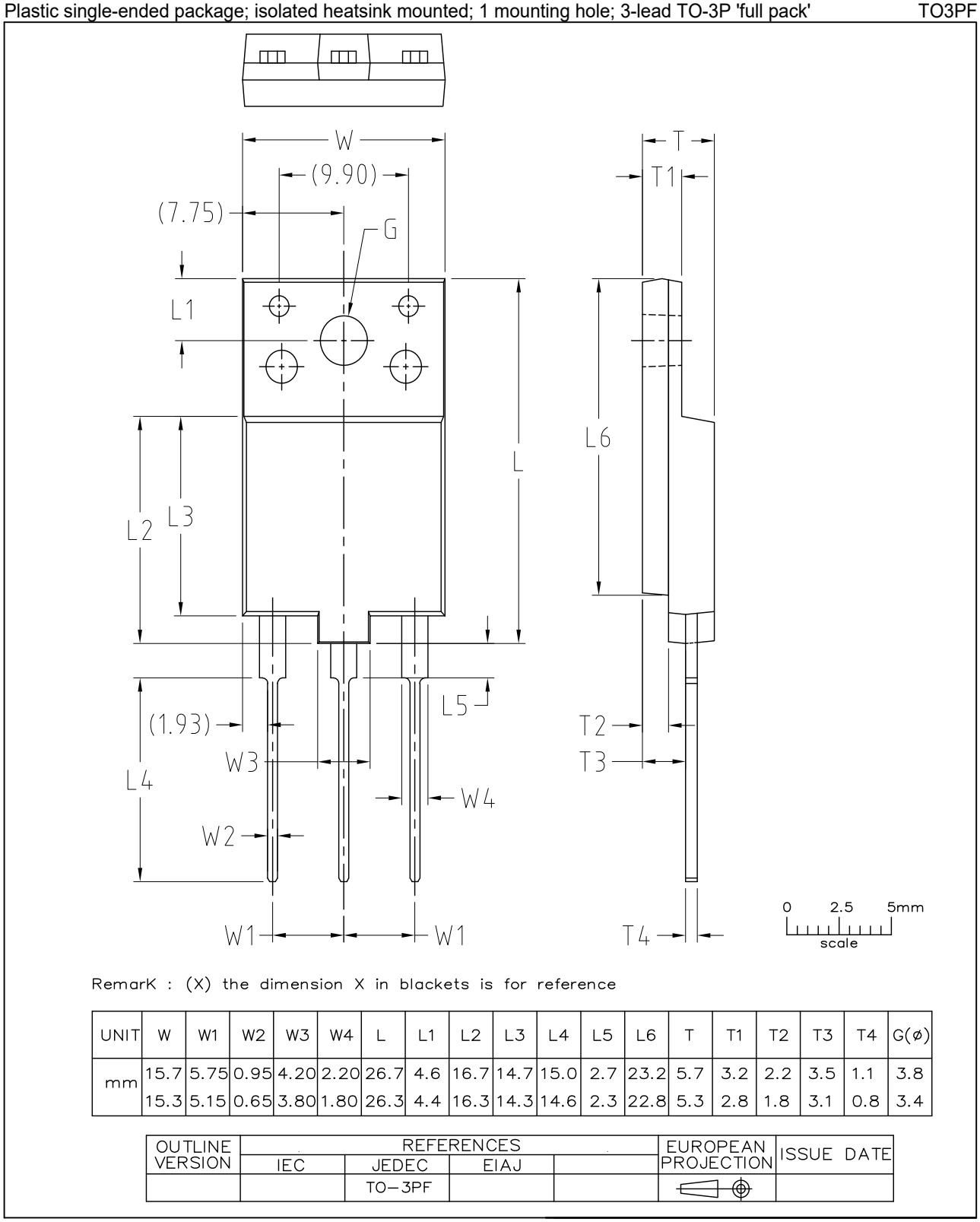
10. Package outline

Plastic single-ended package; isolated heatsink mounted; 1 mounting hole; 3-lead TO-3P 'full pack' TO3PF



RemarK : (X) the dimension X in blackets is for reference

UNIT	W	W1	W2	W3	W4	L	L1	L2	L3	L4	L5	L6	T	T1	T2	T3	T4	G(ø)
mm	15.7	5.75	0.95	4.20	2.20	26.7	4.6	16.7	14.7	15.0	2.7	23.2	5.7	3.2	2.2	3.5	1.1	3.8
	15.3	5.15	0.65	3.80	1.80	26.3	4.4	16.3	14.3	14.6	2.3	22.8	5.3	2.8	1.8	3.1	0.8	3.4

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
		TO−3PF				

Fig. 8. Package outline TO3PF

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